



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



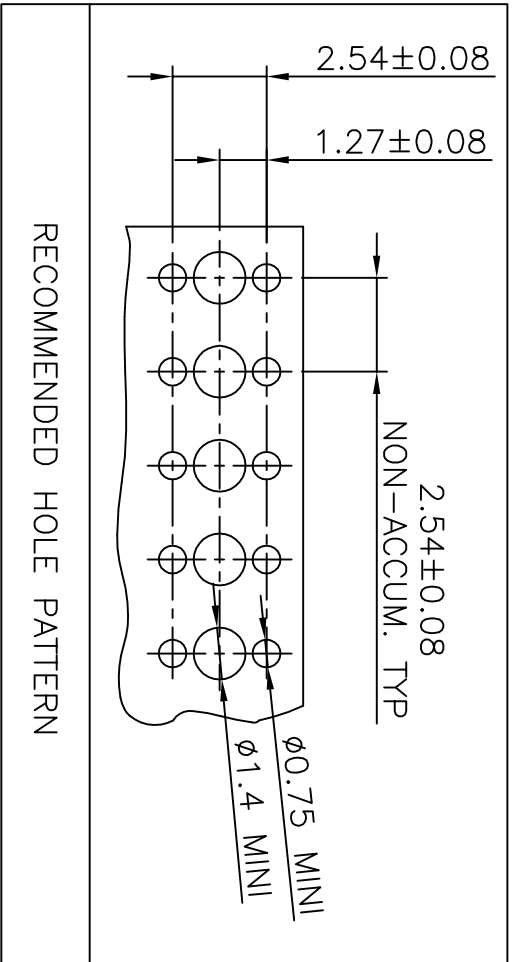
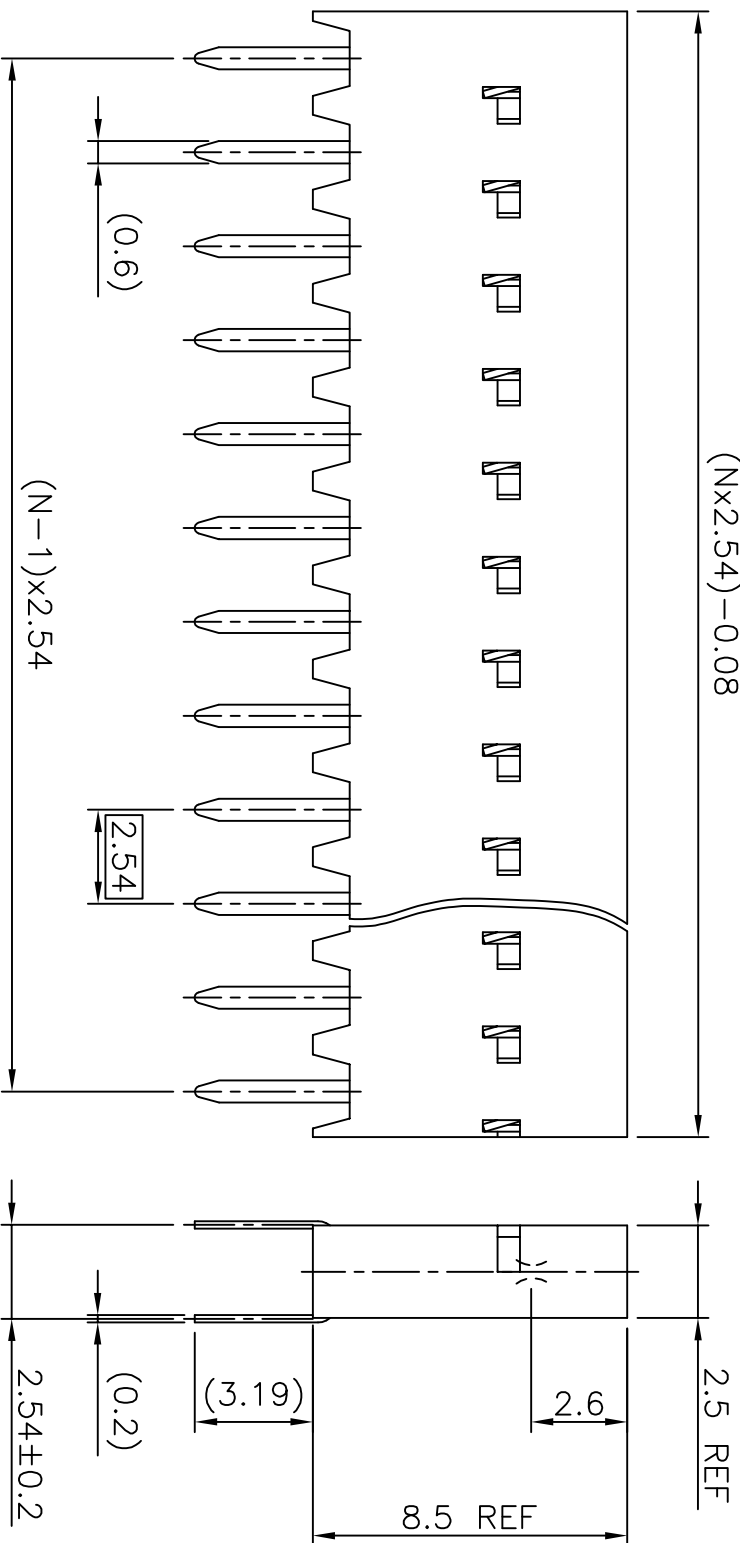
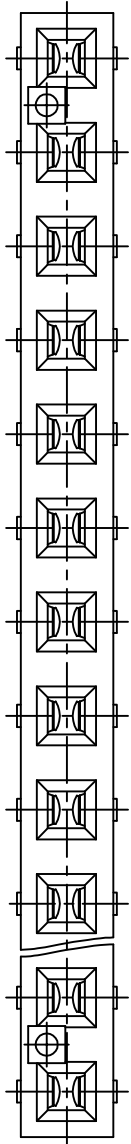
PRODUCT NUMBER
77424-XXXXL

ROHS COMPATIBLE, SEE NOTE 6
NUMBER OF POSITIONS: 02 TO 50.

PLATING CODE
3 = 0.76µm GOLD ON CONTACT AREA.
2µm MIN MATTE TIN ON TAIL.
4 = 2µm MIN MATTE TIN FULL PLATED
1.27µm Ni MIN UNDERPLATING

NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED FLAME RETARDANT PER UL 94 V-0 COLOR: BLUE.
 - 2 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - 3 - 02 UP TO 04 POSITIONS PRODUCT PACKED IN PLASTIC BOX.
05 UP TO 50 POSITIONS PRODUCT PACKED IN TUBE.
 - 4 - TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS
EXAMPLE: 8 POS: (N×2.54)-0.08=20.24 mm
 - 5 - HE13 PRINTING ON 77424-3xx PRODUCT.
 - 6 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS
- d - PLATING:**
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
- b - MANUFACTURING PROCESS COMPATIBILITY**
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- c - LABELING:**
- MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT:** SEE GS-47-0004



ltr	ecrn no	dr	date	surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family
B	F10116	GCO	01.01.23	ISO 1302	ISO 406 ISO 1101	mm	DUBOX
C	F03-0284	DLE	03.10.14	tolerances unless otherwise specified			
D	F04-0153	DLE	04.03.18				
E	F05-0172	DLE	05.04.11				
F	F06-0204	DLE	06.06.21				
G	B-19123	LMU	14.10.21				
H	B-19232	LMU	14.10.28				

mat'l. code	SEE NOTES	surface	tolerance	projection	product family
		ISO 1302	ISO 406 ISO 1101	mm	DUBOX

title	dwg no	sheet 1 of 1	size
BtB RECEIPT. VERT SR TMT	77424		A3